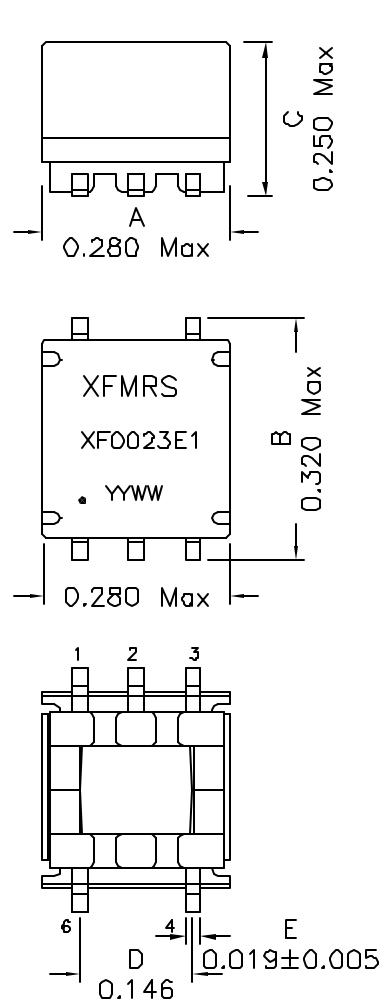
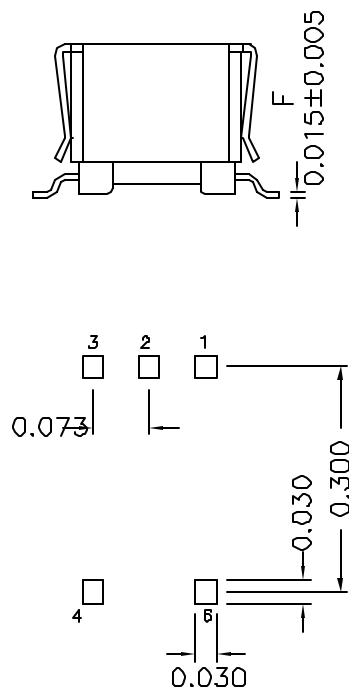


1. Mechanical Dimensions:



(BOTTOM VIEW)



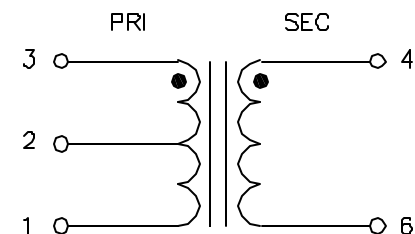
SUGGESTED PAD LAYOUT

Notes:

1. Solderability: Leads shall meet MIL-STD-202G, Method 208H for solderability.
2. Flammability: UL94V-0
3. ASTM oxygen Index: > 28%
4. Insulation System: Class F 155°C. UL file E151556
5. Operating Temperature Range: All listed parameters are to be within tolerance from -40°C to +85°C
6. Storage Temperature Range: -55°C to +125°C
7. Aqueous wash compatible
8. SMD Lead Coplanarity: $\pm 0.004^{\circ}$ (0.102mm)
9. Electrical and mechanical specifications 100% tested
10. RoHS Compliant Component

DOC REV: A/12

2. Schematic:



3. Electrical Specifications:

DCL: Pins 3-1 2.0mH Min @10KHz 0.1V

Q: Pins 3-1 TBD Min @10KHz 0.1V

LL: Pins 3-1 1.2uH Max @100KHz 0.1V,
Short SEC

CW/W: Pins 3-4 50pF Typ @100KHz 0.1V

DCR: Pins 3-1 2.70 Ohms Max

DCR: Pins 4-6 2.60 Ohms Max

LONGITUDINAL BALANCE: 35dB Min @1.544MHz

OPERATION BANDWIDTH: 20KHz-10MHz

RETURN LOSS: 18db Min @50K-3.1MHz

TURNS RATIO: Pins (3-1):(4-6)=1CT:1±1%

HIPOT: 1500Vac, PRI to SEC

XFMRs Inc www.XFMRs.com	Title: T1/E1/ISDN-PRI XFMR		
	UNLESS OTHERWISE SPECIFIED TOLERANCES: .xx ±0.010 Dimensions in Inches		P/N: XF0023E1
Scale 2.5:1 SHT 1 OF 1	DWN.	Juan Mao	Jun-27-08
	CHK.	YK Liao	Jun-27-08
	APP.	BW	Jun-27-08

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